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AT

1 AFTER FINAL

2 I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope  
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*Eugene H. Valet*

PATENT APPLICATION  
DOCKET NO. M085

entered  
w/ RCE  
1/21/05  
T. Young  
1/28/05

7  
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10 IN THE  
11 UNITED STATES PATENT AND TRADEMARK OFFICE

12 GROUP ART UNIT: 2811

13 EXAMINER: Parekh, Nitin

14 INVENTOR(S): Alter, M.

15 SERIAL NO.: 10/648,016

16 CONF. NO.: 3466

17  
18 FILED: 08/26/2003

19 SUBJECT: Semiconductor Devices Integrated with Wafer-Level Packaging

20 REPLY TO OFFICE ACTION AND REQUEST FOR RECONSIDERATION  
21 UNDER 37 CFR 1.116

22 TO: COMMISSIONER FOR PATENTS  
23 POB 1450  
24 ALEXANDRIA, VA 22313

25 SIR:

26 In accordance with the notice "REVISED AMENDMENT PRACTICE: 37 CFR 1.121 CHANGED,  
27 effective July 30, 2003, the MPEP and 37 CFR, following are:

- 28 (A) INTRODUCTORY COMMENTS,  
29 (B) AMENDMENTS TO THE SPECIFICATION,  
30 (C) AMENDMENTS TO THE CLAIMS,  
31 (D) REMARKS, including DRAWING AMENDMENTS, if any.

S/N: 10/648016  
Applicant Docket No.: M085  
Reply to Final